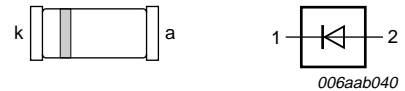


## General description

Single high-speed switching diode, fabricated in planar technology, and encapsulated in a small hermetically sealed glass SOD80C Surface-Mounted Device (SMD) package.

## Features

- High switching speed:  $t_{rr} \leq 4 \text{ ns}$
- Reverse voltage:  $V_R \leq 75 \text{ V}$
- Repetitive peak reverse voltage:  $V_{RRM} \leq 100 \text{ V}$
- Repetitive peak forward current:  $I_{FRM} \leq 450 \text{ mA}$
- Small hermetically sealed glass SMD package



## Applications

- High-speed switching
- Reverse polarity protection

## Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_F$	forward current	[1]	-	-	200	mA
$I_{FRM}$	repetitive peak forward current		-	-	450	mA
$V_R$	reverse voltage		-	-	75	V
$V_F$	forward voltage	$I_F = 100 \text{ mA}$	-	-	1000	mV
$t_{rr}$	reverse recovery time	[2]	-	-	4	ns

## Limiting values

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>RRM</sub>	repetitive peak reverse voltage		-	100	V
V <sub>R</sub>	reverse voltage		-	75	V
I <sub>F</sub>	forward current		[1] -	200	mA
I <sub>FRM</sub>	repetitive peak forward current		-	450	mA
I <sub>FSM</sub>	non-repetitive peak forward current	square wave	[2]		
		t <sub>p</sub> = 1 μs	-	4	A
		t <sub>p</sub> = 1 ms	-	1	A
		t <sub>p</sub> = 1 s	-	0.5	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[1] -	500	mW

**Limiting values**

...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$T_j$	junction temperature		-	200	°C
$T_{amb}$	ambient temperature		-65	+200	°C
$T_{stg}$	storage temperature		-65	+200	°C

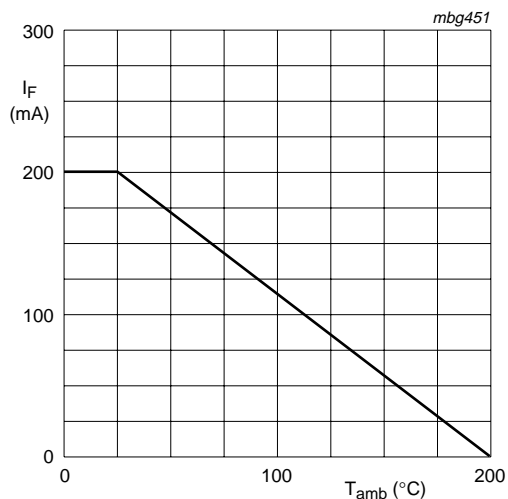
**Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	350	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	300	K/W

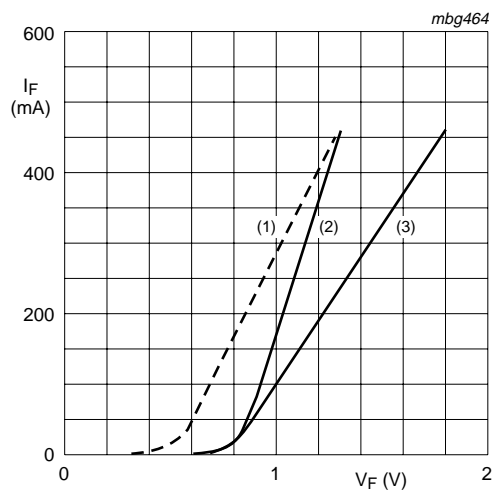
**Characteristics** $T_{amb} = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 5\text{ mA}$	620	-	750	mV
		$I_F = 100\text{ mA}$	-	-	1000	mV
		$I_F = 100\text{ mA}; T_j = 100\text{ °C}$	-	-	930	mV
$I_R$	reverse current	$V_R = 20\text{ V}$	-	-	25	nA
		$V_R = 75\text{ V}$	-	-	5	μA
		$V_R = 20\text{ V}; T_j = 150\text{ °C}$	-	-	50	μA
		$V_R = 75\text{ V}; T_j = 150\text{ °C}$	-	-	100	μA
$C_d$	diode capacitance	$V_R = 0\text{ V}; f = 1\text{ MHz}$	-	-	2	pF
$t_{rr}$	reverse recovery time		[1] -	-	4	ns
$V_{FR}$	forward recovery voltage		[2] -	-	2.5	V

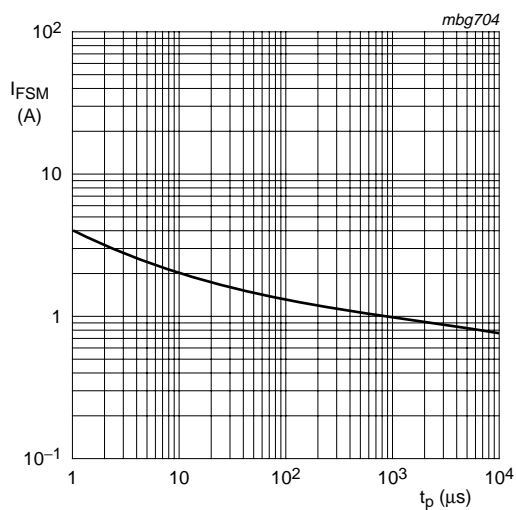
[1] When switched from  $I_F = 10\text{ mA}$  to  $I_R = 10\text{ mA}$ ;  $R_L = 100\text{ Ω}$ ; measured at  $I_R = 1\text{ mA}$ .[2] When switched from  $I_F = 50\text{ mA}$ ;  $t_r = 20\text{ ns}$ .



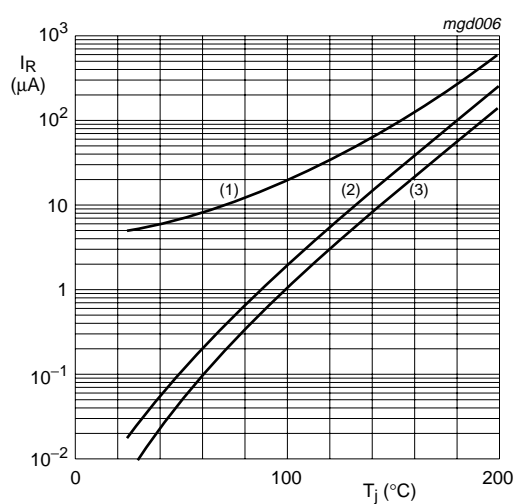
FR4 PCB, standard footprint



- (1)  $T_j = 175 °C$ ; typical values
- (2)  $T_j = 25 °C$ ; typical values
- (3)  $T_j = 25 °C$ ; maximum values



Based on square wave currents.  
 $T_j = 25 °C$  prior to surge



- (1)  $V_R = 75 V$ ; maximum values
- (2)  $V_R = 75 V$ ; typical values
- (3)  $V_R = 20 V$ ; typical values